## SUBMINIATURE THUMBWHEELS SERIES T50 BACK MOUNT


$\mathrm{n}=$ number of modules

$$
\begin{aligned}
& A=(n \times .315)+.945 \\
& B=(n \times .315)+.315 \\
& C=(n \times .315)+.355 \\
& D=(n \times .315)+.655
\end{aligned}
$$

SWITCH CHARACTERISTICS: Dielectric Strength . . . . . . . . 500 VAC Temperature $\qquad$ $-40^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$

For assemblies of more than 10 modules, contact factory. (See page 6)

| Endcaps \& Spacers for T50, T51*, and T52* |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Finish | $.157^{\prime \prime}$ Bezel <br> Endcap | $.315^{\prime \prime}$ Bezel <br> Endcap | $.315^{\prime \prime}$ <br> Spacer | $.315^{\prime \prime} 2 /$ Rib <br> Spacer | $.157^{\prime \prime}$ w/ Rib <br> Spacer |  |
| Black Matte | $609-0980$ | $609-0970$ | $009-0960$ | $609-0990$ | $009-1000$ |  |

Remove excess solder flux with $40 \%$ isopropyl alcohol in distilled water. Other de-fluxing agents may damage switch housings. If you cannot use isopropyl alcohol, contact factory.

